



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



SH Series



Agency Approvals

AGENCY	AGENCY FILE NUMBER
	E128662

Two Electrode GDT Graphical Symbol



Description

The Littelfuse SH Gas Discharge Tubes (GDT) series provides high levels of protection against fast rising transients caused by lightning disturbances. It has a surge rating of 5kA, 8/20 μ s. Offered in a Squared Surface Mount package, which helps to make pick and place on PCB process easier.

This GDT series is perfectly suited for broadband equipment applications. The GDT's low off-state capacitance is compatible with high bandwidth applications and this capacitance loading value does not vary if the voltage across the GDT changes.

The Littelfuse SH Gas Discharge Tube (GDT) series are specifically designed for protection of electrical, multimedia, and communication equipment against over voltage transients in surface mount assembly applications.

Features

- Excellent response to fast rising transients
- GHz working frequency
- 5kA, 8/20 μ s surge capability as defined by IEC 61000-4-5, 2nd Edition
- UL Recognized
- Offered with squared body package
- Non-Radioactive
- Ultra Low capacitance (<0.7pF)
- Lead-free and RoHS compliant

Applications

- CATV equipment
- Antennas
- RS 485
- Telecom Base Station
- Power Supply AC Main
- G.fast
- EV power Charging
- Inverter/Variable Frequency Drivers (VFDs)
- IEEE 802.3 compliant Ethernet interfaces
- Broad Band equipment
- xDSL, ADSL, ADSL2, VDSL, and VDSL2
- Medical Electronics
- Test Equipment
- General Telecom Equipment
- Renewable Energy

Electrical Characteristics

Part Number	Component Specifications (at 25°C)								Life Ratings				
	DC Breakdown in Volts (@100V/s)			Maximum Impulse Break-down Voltage		Maximum Impulse Discharge Current (8/20µs)	Insulation Resistance	Capacitance (@1MHz)	Impulse Discharge Current (8/20µs)	AC Discharge Current (50Hz, 1sec)	AC Discharge Current (9 Cycles @50Hz)	DC Holdover Voltage (<150ms)*	Impulse Life (10/1000µs) (100A)
	MIN	TYP	MAX	@100V/µs	1000V/µs	1 Time	MIN	MAX	MAX	MIN	MIN		MIN
SH75	60	75	90	600	700	6kA	1GΩ @50V	0.7pf	10 Shots @ (5kA)	5A	15A	52V	300 Shots
SH90	72	90	108	600	700		52V						
SH145	116	145	174	600	700		52V						
SH230	184	230	276	600	700		80V						
SH250	200	250	300	600	700		135V						
SH300	240	300	360	650	800		135V						
SH350	280	350	420	750	900		135V						
SH400	320	400	480	850	1000		135V						
SH470	376	470	564	900	1100		150V						
SH600	480	600	720	1000	1200		150V						

Note:
 * Reference REA PE-80, 0.2A, tested to ITU-T Rec K.12 and REA PE 80 <150 ms.
 ** DC spark-over may exceed ± 25% after discharge, but will continue to protect without venting

Product Characteristics

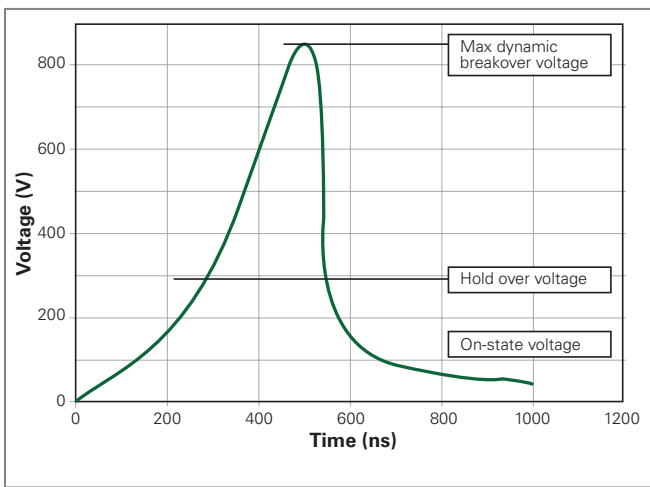
Materials	Device Tin Plated 17.5 ± 12.5 Microns Construction: Ceramic Insulator
Storage and Operational Temperature	-40 to +90°C

Typical Insertion Loss

@1.0GHz = 0.08dB
@1.4GHz = 0.16dB
@1.8GHz = 0.26dB
@2.0GHz = 0.33dB
@2.4GHz = 0.47dB
@2.8GHz = 0.59dB
@3.1GHz = 0.70dB
@3.5GHz = 0.89dB
@4.0GHz = 1.24dB

Note: Insertion data for customer reference only, application testing needed for verification.

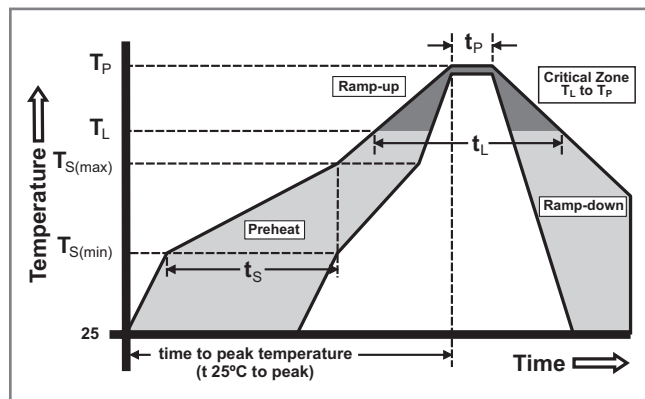
Voltage Vs. Time Characteristic



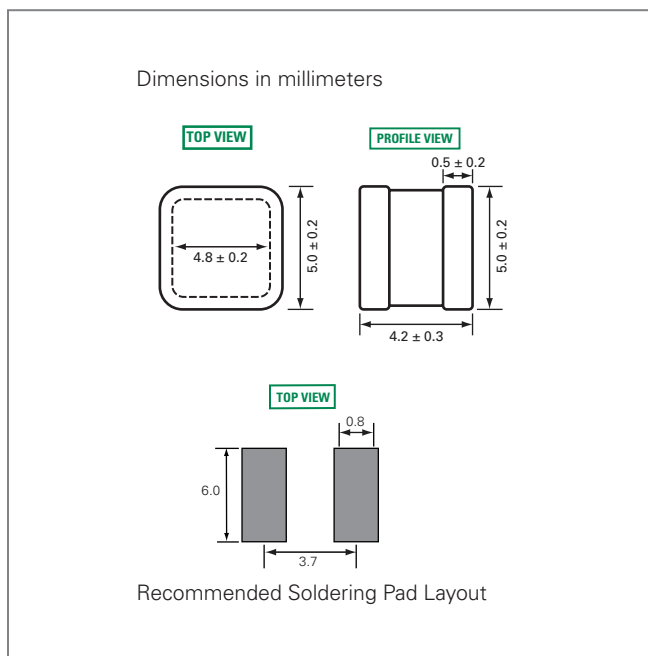
Note: Tested per 1kV/µs waveform

Soldering Parameters - Reflow Soldering (Surface Mount Devices)

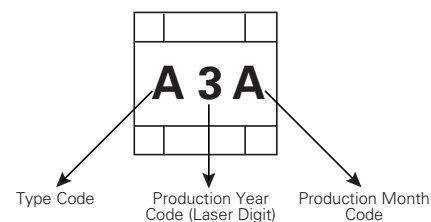
Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		10 – 30 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



Product Dimensions



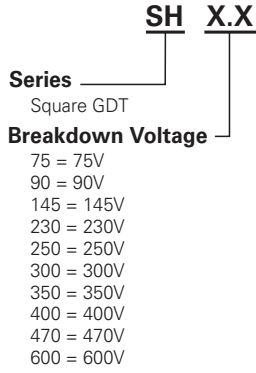
Product Marking



Type Code	
A	SH75
B	SH90
S	SH145
D	SH230
R	SH250
E	SH300
G	SH350
I	SH400
P	SH470
V	SH600

Month Code	
A	January
B	February
C	March
D	April
E	May
F	June
G	July
H	August
I	September
J	October
K	November
L	December

Part Numbering System and Ordering Information

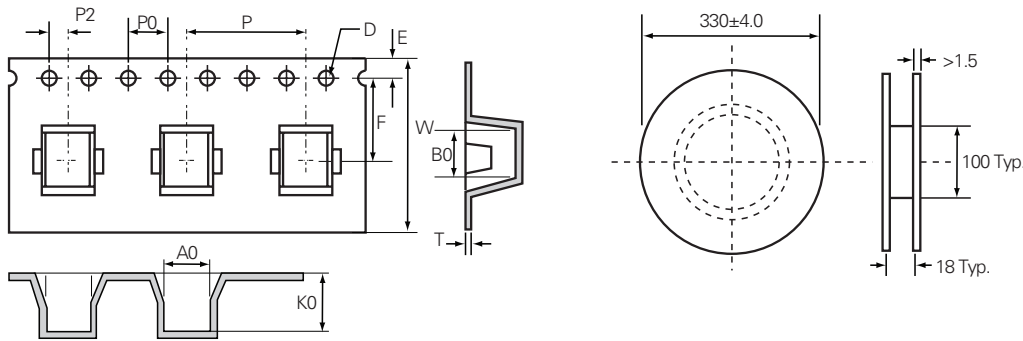


Taping and Reel Specifications

Taping

Unit = mm

Item	A0	B0	K0	P0	P	P2
Spec	4.6±0.1	5.4±0.1	5.4±0.2/-0.1	4.0±0.1	12.0±0.1	2.0±0.15
Item	E	F	D	W	T	
Spec	1.75±0.1	7.5±0.1	1.5±0.1/-0.5	16.0±0.3	0.5±0.1	



Packaging Quantity:

- 900 pcs per reel (13")
- 1 reel per inner box
- 10 inner boxes per carton
- 9,000 pcs per full carton